

-30V P-Channel Enhancement Mode MOSFET

Description

The AP3407CI uses advanced Trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -30V$ $I_D = -3.6A$

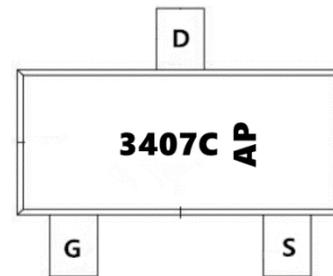
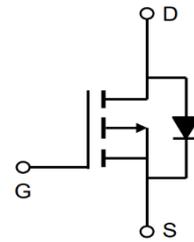
$R_{DS(ON)} < 85m\Omega$ @ $V_{GS}=10V$ (Type: 70m Ω)

Application

Battery protection

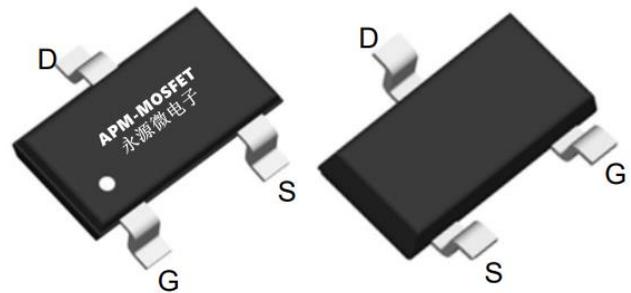
Load switch

Uninterruptible power supply



Top View

Bottom View



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP3407CI	SOT23L	3407C-AP	3000

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-4.8	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.3	A
IDM	Pulsed Drain Current ^{note1}	-20.4	A
P_D	Power Dissipation $T_A = 25^\circ C$	2.15	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	104	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance from Junction to Ambient ²	125	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$

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Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-30	-33		V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	μA
IGSS	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
VGS(th)	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =-250μA	-1.0	-1.5	-2.4	V
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-3A		70	85	mΩ
		V _{GS} =-4.5V, I _D =-2A		100	120	
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHZ		365		pF
C _{oss}	Output Capacitance			59		
C _{rss}	Reverse Transfer Capacitance			45		
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-3A		7.6		nC
Q _{gs}	Gate-Source Charge			1.64		
Q _{gd}	Gate-Drain Charge			1.22		
Q _{rr}	Reverse Recovery Charge	I _F =-3A, di/dt=100A/μs		3.8		
t _{rr}	Reverse Recovery Time			25		
tD(on)	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-15V, I _D =-1A R _{GEN} =2.5Ω		3.2		ns
t _r	Turn-on Rise Time			17.8		
tD(off)	Turn-off Delay Time			18		
t _f	Turn-off fall Time			23.2		
V _{SD}	Diode Forward Voltage	I _S =-3A, V _{GS} =0V			-1.2	V

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

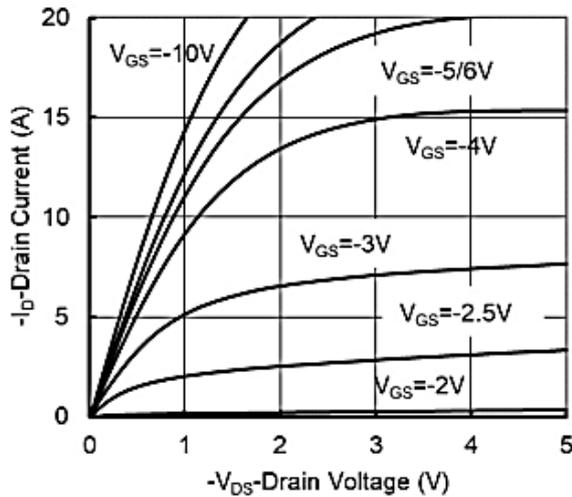


Figure1. Output Characteristics

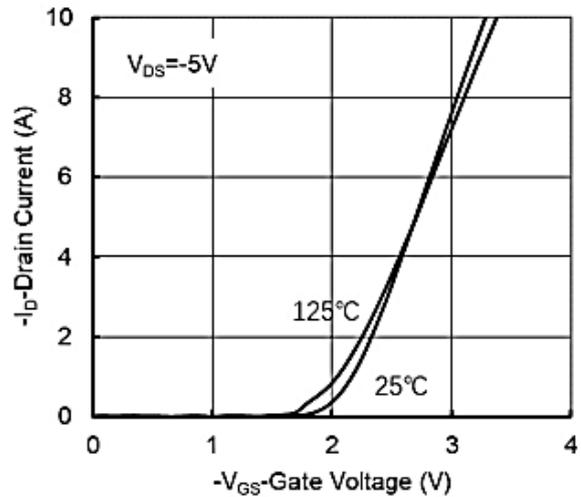


Figure2. Transfer Characteristics

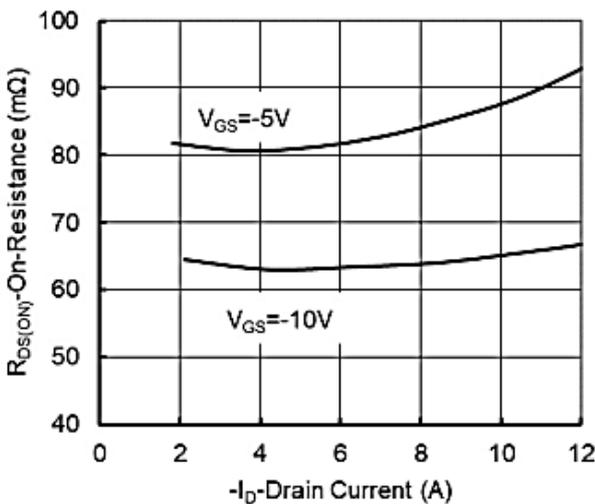


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

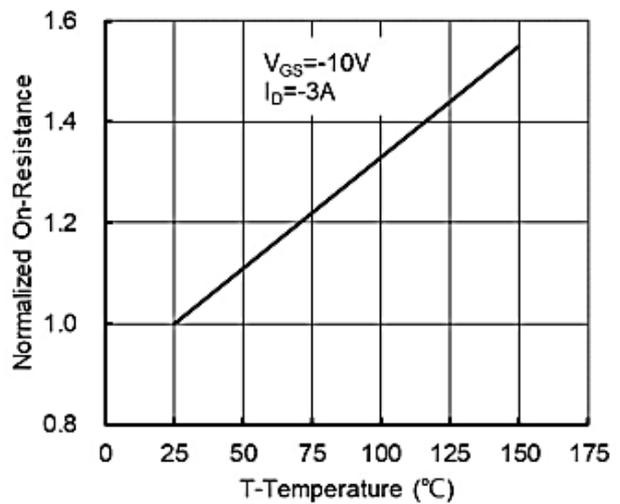


Figure 4: On-Resistance vs. Junction Temperature

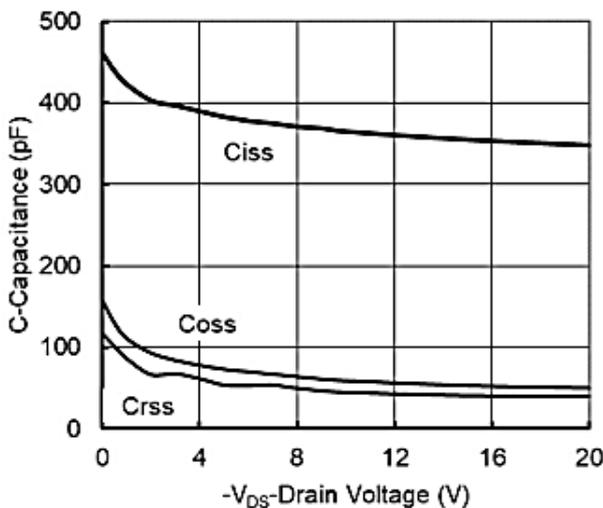


Figure5. Capacitance Characteristics

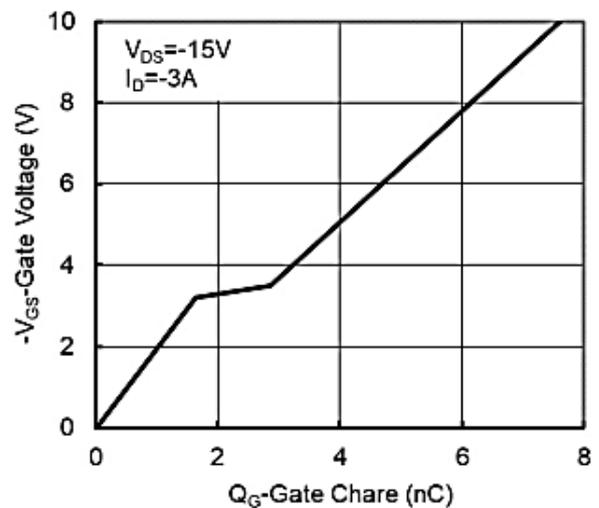


Figure6. Gate Charge



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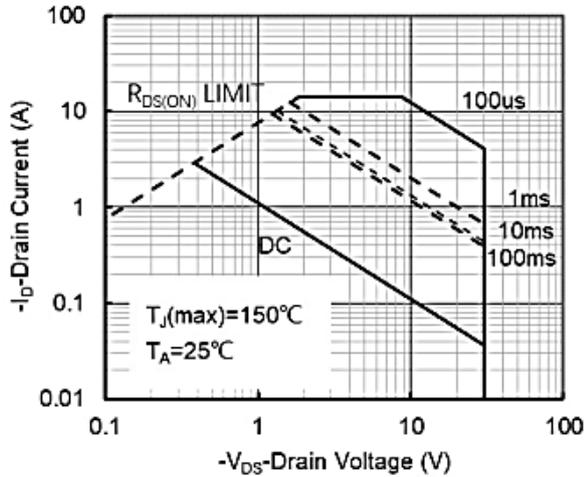


Figure 7. Safe Operation Area

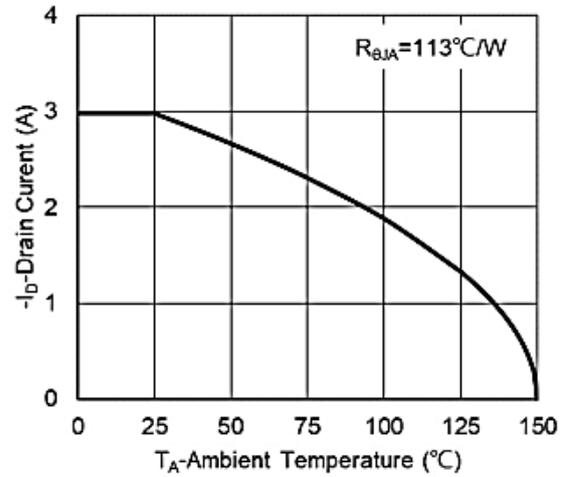


Figure 8. Maximum Continuous Drain Current vs Ambient Temperature

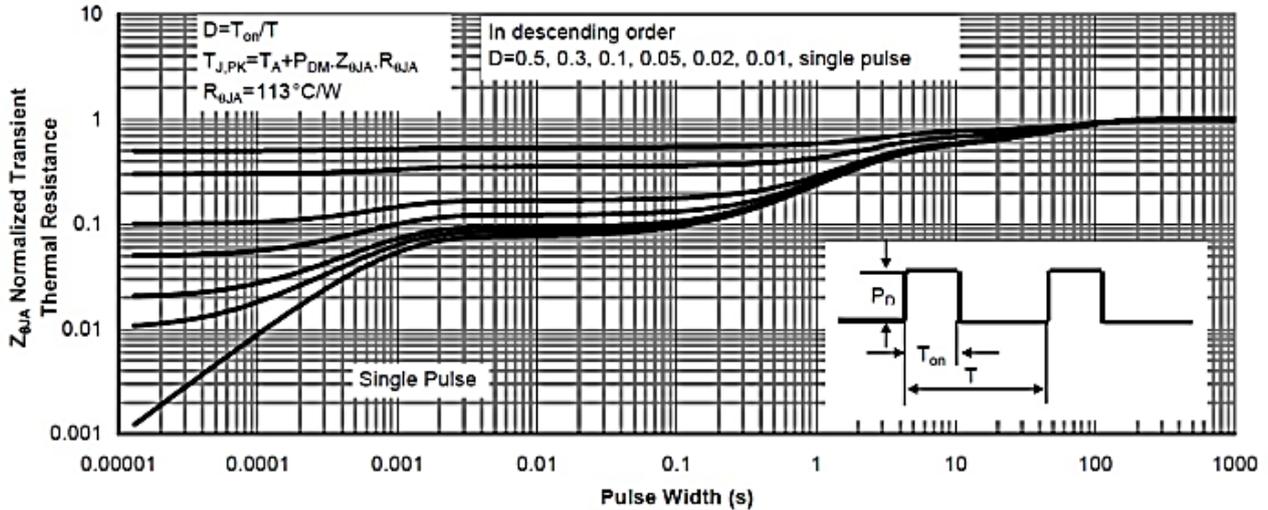


Figure 9. Normalized Maximum Transient Thermal Impedance

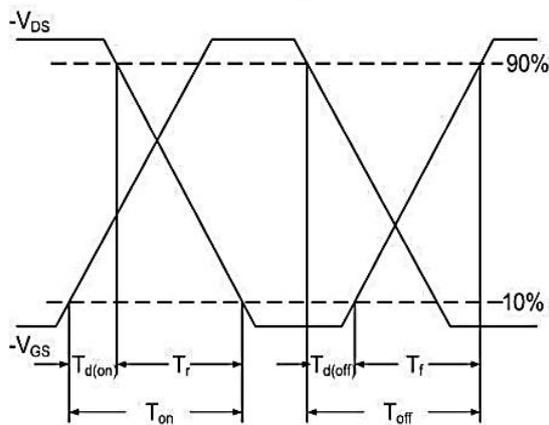


Figure 10. Switching Time Waveform

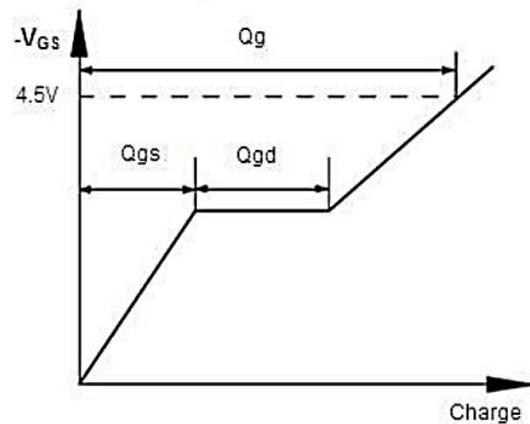
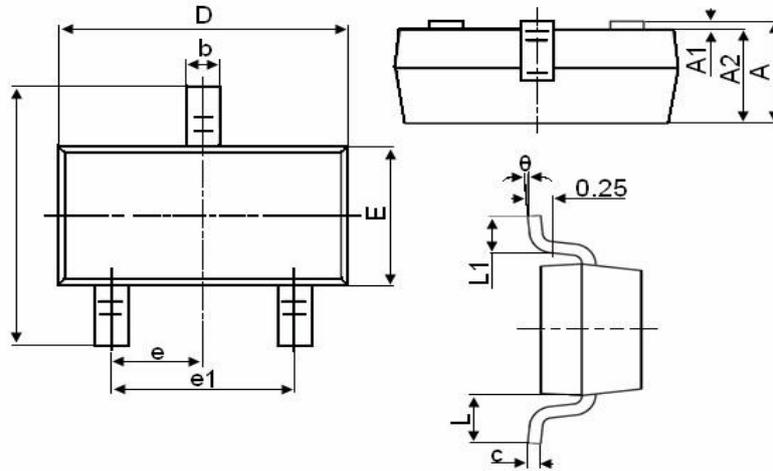


Figure 11. Gate Charge Waveform

Package Mechanical Data-SOT23-XC-Single



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

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Edition	Date	Change
Rve1.0	2018/11/31	Initial release

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